

PATENT ABSTRACTS OF JAPAN

(11)Publication number : 07-074251

(43)Date of publication of application : 17.03.1995

(51)Int.Cl.

H01L 21/78
H01L 21/027
H01L 21/60

(21)Application number : 05-240304

(71)Applicant : SONY CORP

(22)Date of filing : 02.09.1993

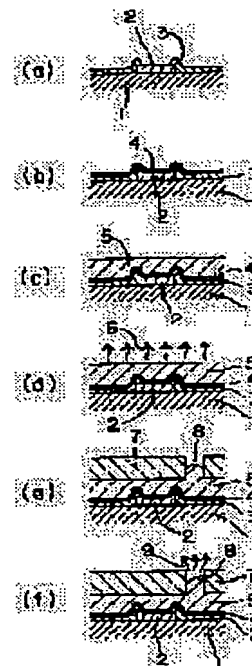
(72)Inventor : ITOU MUTSUSADA

(54) FORMATION OF BUMP ON SEMICONDUCTOR DEVICE

(57)Abstract:

PURPOSE: To allow formation of good bumps for all devices by coating an underlying material with a photosensitive liquid resist and then laminating a photosensitive dry film resist thereon.

CONSTITUTION: An underlying material, i.e., a barrier metal 4, is formed on a semiconductor wafer 1 provided with an Al pad 2 and a passivation film 3. The barrier metal 4 is then spin coated with a photosensitive liquid resist 5 with a thickness corresponding to the height of the bump and then it is heated and temporarily dried until 49-90% of solvent is gasified 6. Subsequently, photosensitive dry film resist 7 having uniform thickness is applied to the temporarily dried fluid resist 5 and laminated by thermocompression such that the surface of the photosensitive liquid resist 5 is planarized uniformly. Crowns existing on the periphery of the semiconductor wafer 1 are pushed into holes 8 along with excess resist through the thermocompression thus bringing about uniform total thickness over the entire surface of resist 5.



LEGAL STATUS

[Date of request for examination] 29.08.2000

[Date of sending the examiner's decision of rejection]

[Kind of final disposal of application other than the examiner's decision of rejection or application converted registration]

[Date of final disposal for application]

[Patent number] 3326779

[Date of registration] 12.07.2002

[Number of appeal against examiner's decision of rejection]

[Date of requesting appeal against examiner's